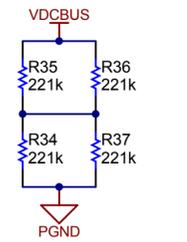
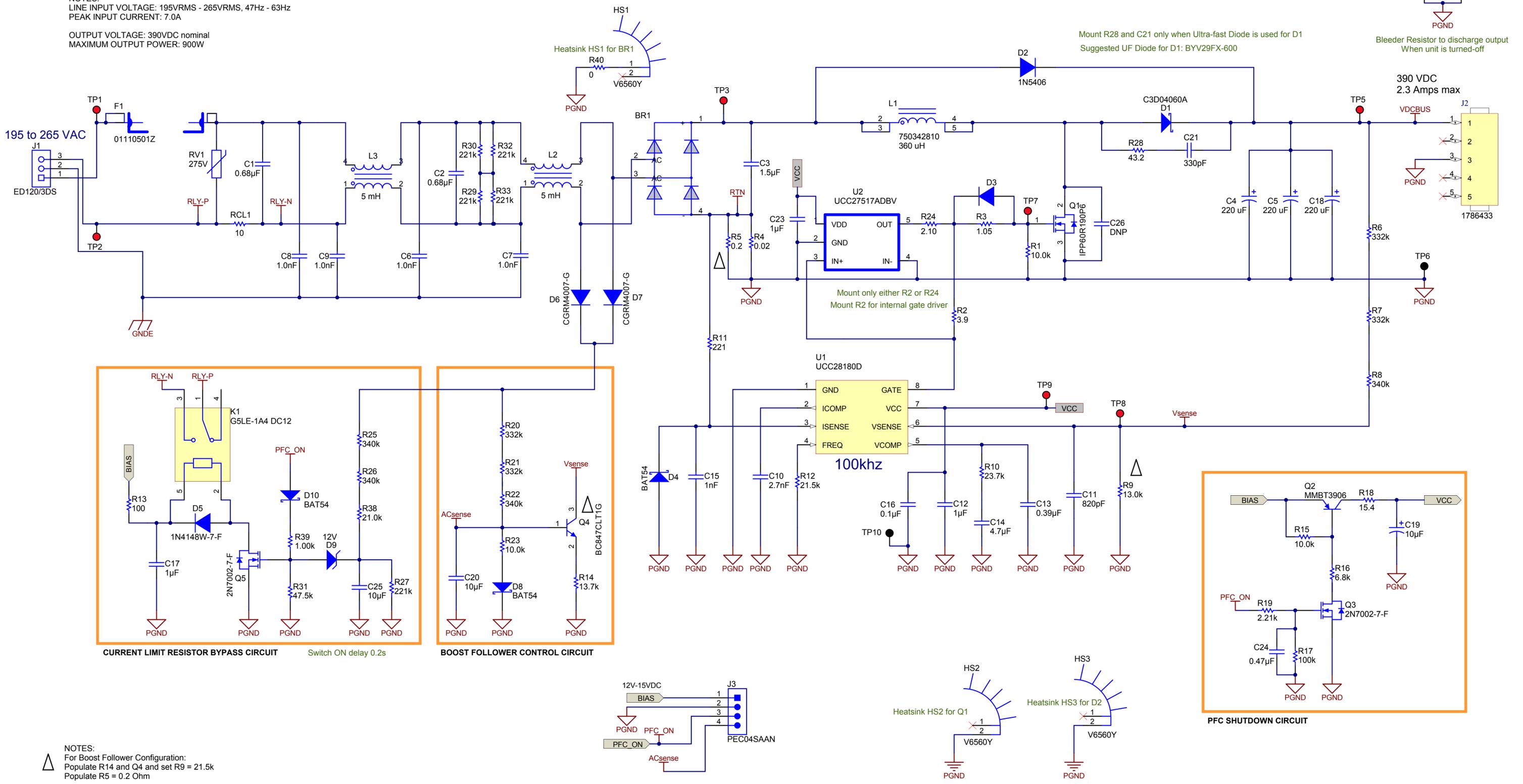


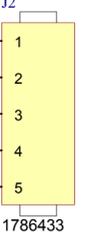
NOTES:  
 LINE INPUT VOLTAGE: 195VRMS - 265VRMS, 47Hz - 63Hz  
 PEAK INPUT CURRENT: 7.0A

OUTPUT VOLTAGE: 390VDC nominal  
 MAXIMUM OUTPUT POWER: 900W



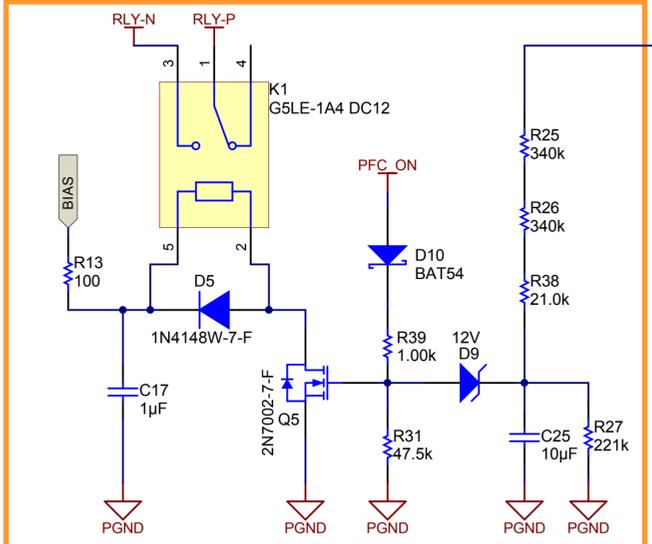
Bleeder Resistor to discharge output  
 When unit is turned-off

390 VDC  
 2.3 Amps max

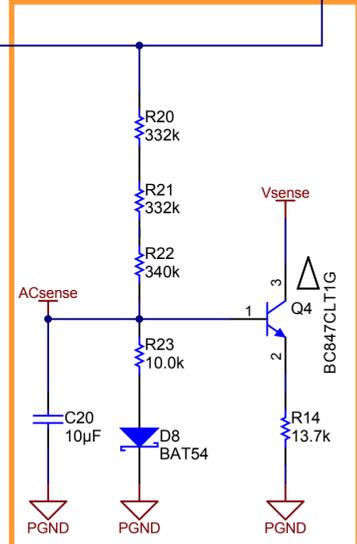


Mount R28 and C21 only when Ultra-fast Diode is used for D1  
 Suggested UF Diode for D1: BYV29FX-600

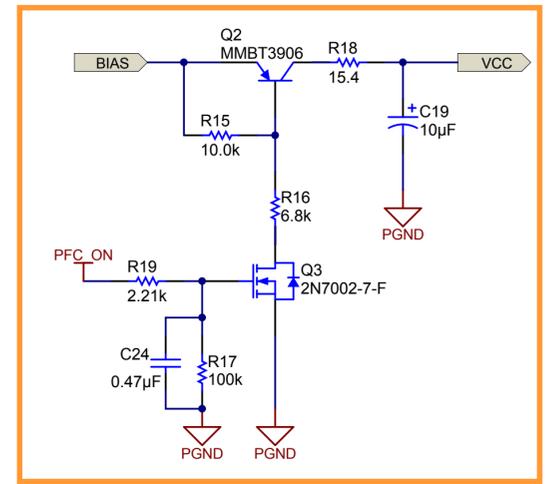
Mount only either R2 or R24  
 Mount R2 for internal gate driver



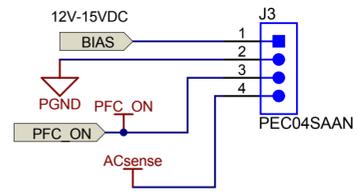
CURRENT LIMIT RESISTOR BYPASS CIRCUIT Switch ON delay 0.2s



BOOST FOLLOWER CONTROL CIRCUIT



PFC SHUTDOWN CIRCUIT



Recommended to use TIDA-00434 Design for Bias Supply Needs

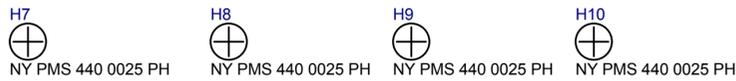
NOTES:  
 For Boost Follower Configuration:  
 Populate R14 and Q4 and set R9 = 21.5k  
 Populate R5 = 0.2 Ohm

For Fixed Output Boost PFC configuration  
 Do not populate R14 and Q4 and Set R9 = 13k  
 Do not populate R5

Orderable: TIDA-00443	Designed for: Public Release	Mod. Date: 6/15/2015
TID #: TIDA-00443	Project Title: 900W PFC Pre-Regulator for Inverter Fed Drives	Sheet Title:
Number: TIDA-00443	Rev: E1	Sheet: 1 of 2
SVN Rev: Not in version control	Assembly Variant: 001	Size: B
Drawn By: Latif Ameer	File: TIDA-00443_REV.B_SchDoc	Contact: http://www.ti.com/support
Engineer: Latif Ameer		

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PCB Number: TIDA-00443  
PCB Rev: E2

PCB  
LOGO  
Texas Instruments

PCB  
LOGO  
Pb-Free Symbol

**You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.**

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
**Label Assembly Note**  
This Assembly Note is for PCB labels only

ZZ2  
**Assembly Note**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
**Assembly Note**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
**Assembly Note**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: TIDA-00443	Designed for: Public Release	Mod. Date: 6/1/2015
TID #: TIDA-00443	Project Title: 900W PFC Pre-Regulator for Inverter Fed Drives	
Number: TIDA-00443	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 2 of 2
Drawn By: Latif Ameer	File: TID_Hardware_SchDoc	Size: B
Engineer: Latif Ameer	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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